MA3Z792 (MA792)

Silicon epitaxial planar type

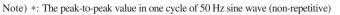
For super high speed switching For small current rectification

Features

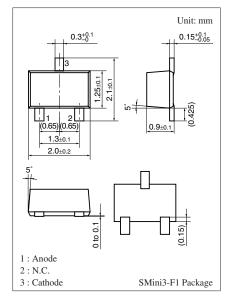
- High-density mounting is possible
- Forward current (Average) $I_{F(AV)} = 100$ mA rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- \bullet Low forward voltage $V_{\rm F}$ and good rectification efficiency

Symbol	Rating	Unit
V _R	30	V
V _{RRM}	30	V
I _{FM}	300	mA
I _{F(AV)}	100	mA
I _{FSM}	1	А
Tj	125	°C
T _{stg}	-55 to +125	°C
	V _R V _{RRM} I _{FM} I _{F(AV)} I _{FSM} T _j	$\begin{tabular}{ c c c c c c } \hline V_R & 30 \\ \hline V_{RRM} & 30 \\ \hline I_{FM} & 300 \\ \hline I_{F(AV)} & 100 \\ \hline I_{FSM} & 1 \\ \hline T_j & 125 \\ \hline \end{tabular}$

Absolute Maximum Ratings $T_a = 25^{\circ}C$

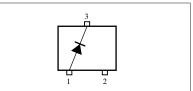


Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$



Marking Symbol: M3T

Internal Connection

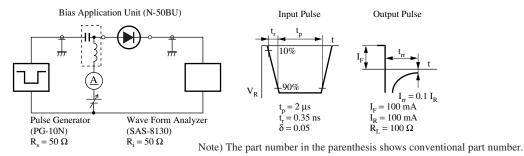


Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I _R	$V_R = 30 V$			15	μΑ
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		20		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		2.0		ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

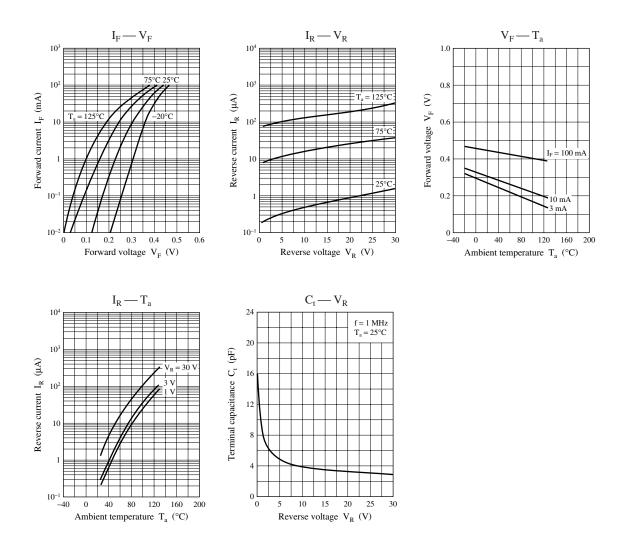
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz.





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